

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

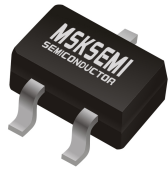
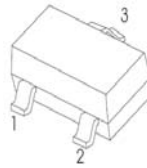


GDT



PLED

Product data sheet


SOT - 23


1. BASE
2. EMITTER
3. COLLECTOR

2SC2712 TRANSISTOR (NPN)

FEATURE

- Audio Frequency General Purpose Amplifier Applications
- Low Noise: NF=1 dB (Typ), 10dB(MAX)
- Complementary to 2SA1162

MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CB0}	Collector-Base Voltage	60	V
V _{CEO}	Collector-Emitter Voltage	50	V
V _{EBO}	Emitter-Base Voltage	5	V
I _C	Collector Current -Continuous	150	mA
P _C	Collector Power Dissipation	150	mW
T _J , T _{stg}	Operation Junction and Storage Temperature Range	-55-150	°C

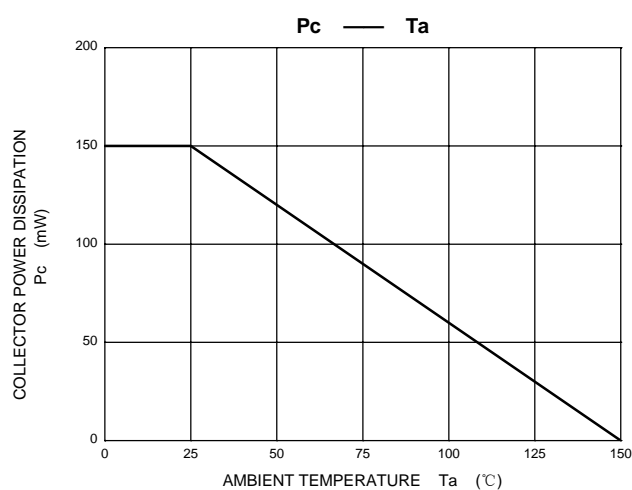
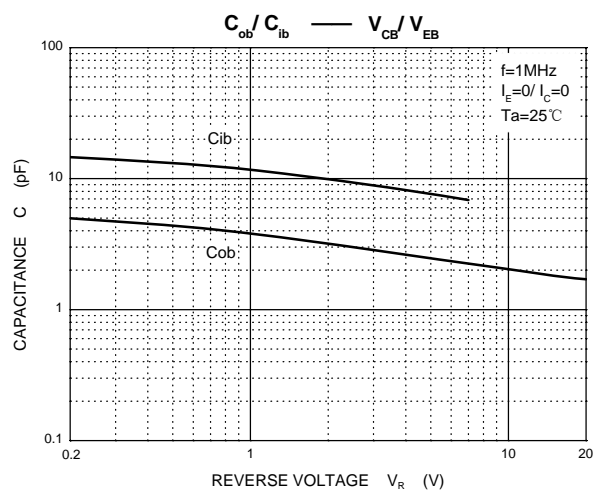
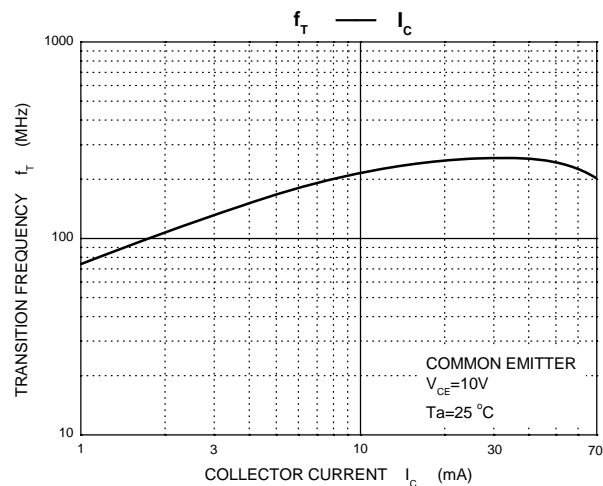
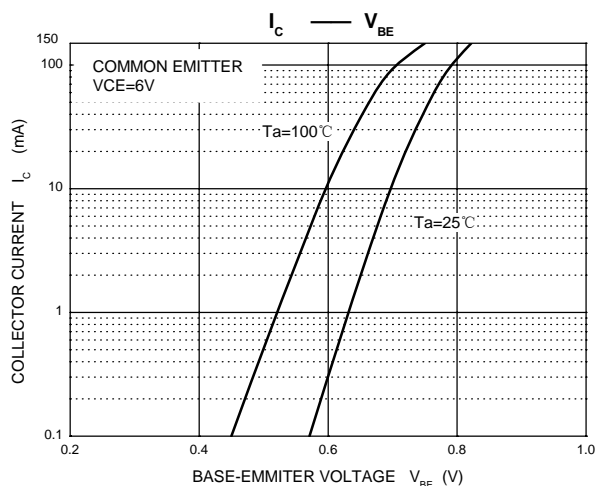
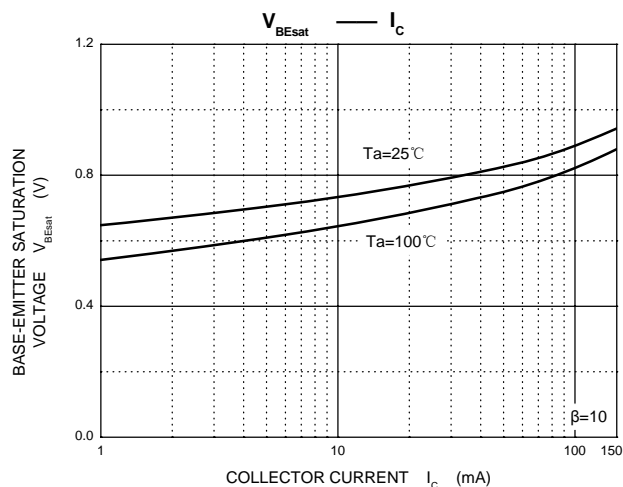
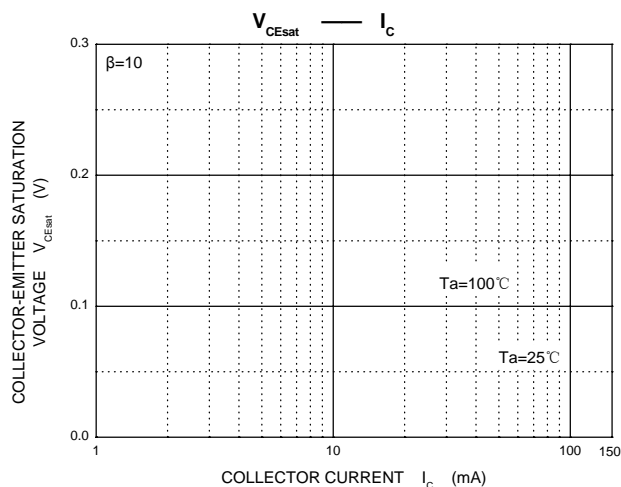
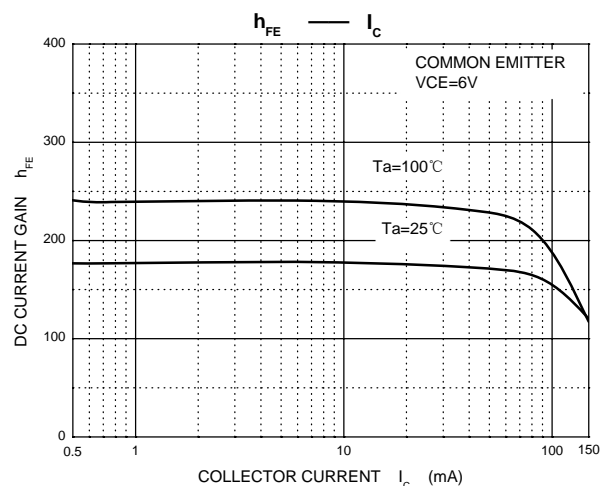
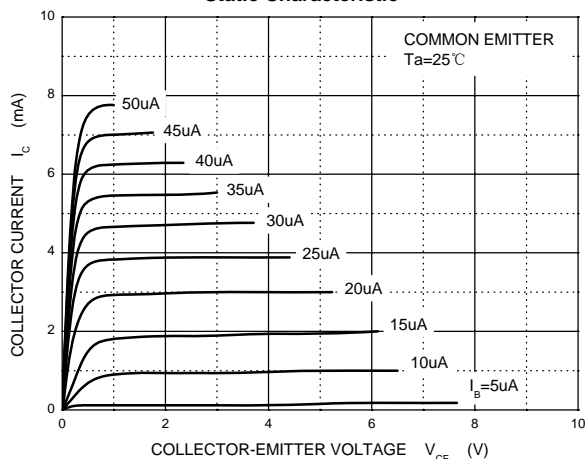
ELECTRICAL CHARACTERISTICS (T_a=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C = 100μA, I _E =0	60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	50			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = 100μA, I _C =0	5			V
Collector cut-off current	I _{CBO}	V _{CB} = 60 V, I _E =0			0.1	μA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			0.1	μA
DC current gain	h _{FE}	V _{CE} =6V, I _C =2mA	70		700	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 100mA, I _B =10mA		0.1	0.25	V
Transition frequency	f _T	V _{CE} =10V, I _C = 1mA	80			MHz
Output capacitance	C _{ob}	V _{CB} =10V, I _E =0, f=1 MHz		2.0	3.5	pF
Noise Figure	NF	V _{CE} =6V, I _C =0.1mA, f=1kHz, R _g =10kΩ		1.0	10	dB

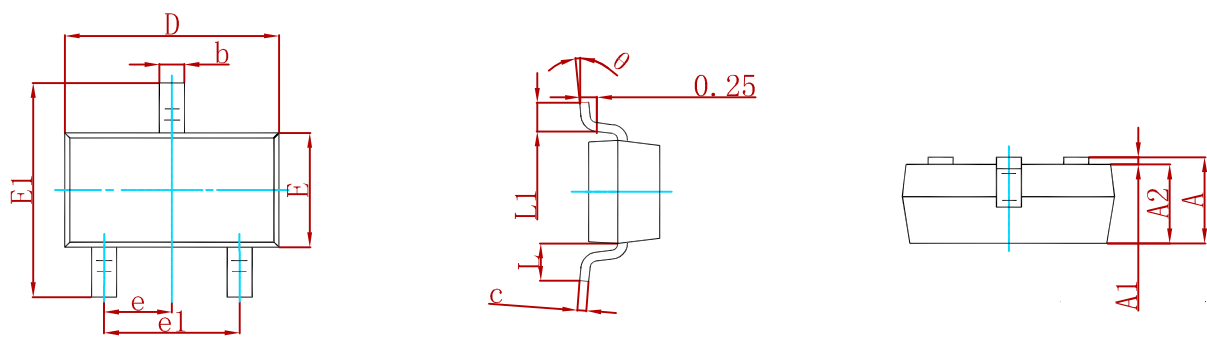
CLASSIFICATION OF h_{FE}

Rank	O	Y	GR	BL
Range	70-140	120-240	200-400	350-700
Marking	LO	LY	LG	LL

Static Characteristic

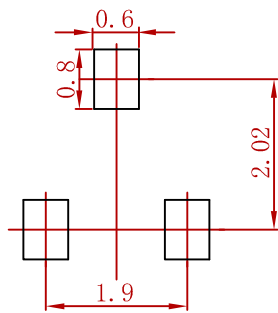


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:
- 1.Controlling dimension:in millimeters.
 - 2.General tolerance:± 0.05mm.
 - 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
2SC2712	SOT-23	3000

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